

Features

When BGA devices are transitioned to Lead-free packages, OEMs with RoHS exempt applications are faced with costly PC board redesign and/or the added cost and time delays associated with re-qualifying the board soldering profile. BGA Interposers and Socket Adapter Systems from Advanced are cost-effective methods for converting Lead-free BGA device packages for use on boards processed with traditional Tin/Lead solder reflow profiles.

- Reduces costs associated with device package transition or obsolescence.
- Solutions available for both RoHS compliant and exempt applications.
- Industry proven screw-machined terminals with solder balls provide the high reliability required in medical, military, telecom, and automotive applications.
- Same footprint as BGA device.
- Device attach services available in-house.
- Tape and Reel packaging available.

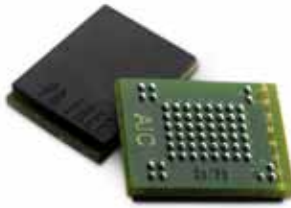
Specifications

Solder Ball:

Lead-free: 95.5Sn/4.0Ag/0.5Cu
Standard: 63Sn/37Pb

BGA Interposers

Table of Models



Description: Interposers are application specific
Material: FR-4 Fiberglass Epoxy Board

Custom BGA Interposer

BGA Interposers from Advanced Interconnections are a cost effective method for converting Lead-free BGA device packages for use on boards processed with lower temperature, Tin/Lead solder profiles.

Designed for RoHS exempt applications, Interposers solve BGA device transition, obsolescence, and solderability issues associated with the higher temperature requirements to process Lead-free BGA packages.

How It Works

Advanced's turn-key solution consists of Lead-free BGA device attach to an Interposer adapter board in a high temperature reflow process, followed by mounting of eutectic (63/37) Tin/Lead solder balls on the bottom of the Interposer. The compact Interposer assembly is shipped ready for use on existing PC boards, eliminating the need to change Tin/Lead solder profiles or subject other components to higher processing temperatures.

